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FM52985  
ISO 9001:2000

**Quick Turn IC Assembly, Pre-Asia Volume Production, Custom Packaging**

<b>IC ASSEMBLY - PLASTIC PACKAGES: Commercial, MIL-STD-883, Si GaAs InP Devices</b>			
Package Type	Lead Count	Body Size	Solder
SOIC	8, 16 (heat sink option)	0.150"	Plate
	14	0.150"	Plate
	16, 20, 24, 28	0.300"	Coat
QSOP	16 (heat sink option)	0.150"	Plate
SSOP	30	5.3 mm	Plate
MSOP	8, 10	3.0 mm	Plate
TSSOP	20, 28	4.4 mm	Plate
PDIP	14, 16, 20, 24, 28	0.300"	Coat
	24, 28, 40	0.600"	Coat

<b>QFN, TQFN, DFN: JEDEC MO-220, MO-229, stacked die, SiP &amp; MEMS RoHS compliant, custom versions in 4 – 5 weeks, copper wire bonding available</b>					
Size (mm)	QFN Lead Count	DFN Lead Count	Pitch (mm)	QFN Height (mm)	TQFN
2x2		6, 8, 10	0.50	0.90 nom.	0.75 nom.
2x3		10, 12	0.50	0.90	0.75
3x3	8 / 12, 16 / 20	8, 10	0.65 / 0.50 / 0.40	0.90	0.75
3x4		12	0.50	0.90	0.75
4x4	16 / 20, 24	12	0.65 / 0.50	0.90	0.75
5x5	20 / 28, 32 / 36, 40		0.65 / 0.50 / 0.40	0.90	0.75
6x6	40 / 48		0.50 / 0.40	0.90	0.75
7x7	48 / 56		0.50 / 0.40	0.90	0.75
8x8	52, 56 / 68		0.50 / 0.40	0.90	0.75
9x9	64		0.50	0.90	0.75
10x10	72		0.50	0.90	0.75
12x12	100		0.40	0.90	0.75

<b>IC ASSEMBLY – CERAMIC PACKAGES</b>	
Multilayer	8L through 447 L packages
PGA (pin up & pin down), LCC, Flat Pack, QFP, DIP	
Die attach: Eutectic, Polyimide, JM7000, Epoxy Wire Bond: Al, Au, Cu (0.8 - 2 mil standard)	
Seal: Solder (AuSn), Glass, Adhesive	
CDIP, CQUAD, CPAC:	8L through 256L packages
Die attach: Eutectic, Polyimide Wire bond: Ultrasonic Al Seal: Glass Lead finish: Solder coat	

<b>CUSTOM PACKAGING &amp; OTHER SERVICES</b>	
SiP: 2D system, 3D system, flip chip, SMT – over molded	
CSP, Multi-Chip (MCM) & RF Modules, Hybrid Assembly	
Chip-on-Board (COB), Chip-on-Flex (COF), Flip Chip Technologies including ACF	
Wafer dicing & die processing: Commercial & MIL-STD-883 Condition A (Class S) & Condition B “pizza” wafers, shuttle die, 300 mm wafer processing	
Wire bonding: Au ball, Au wedge, Al wedge, Copper, controlled loop RF wedge, Ribbon	

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**Silicon Valley’s Packaging Foundry**